

Description

The HBSS138AKAR uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

 V_{DS} = 60V I_D =0.3A

 $R_{DS(ON)} < 2\Omega @ V_{GS}=10V$

ESD Rating: HBM≥2000V

Application

Battery protection

Load switch

Uninterruptible power supply

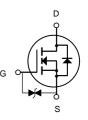
Package Marking and Ordering Information

| Product ID | Pack | Marking | Qty(PCS) |
|-------------|--------|----------|----------|
| HBSS138AKAR | SOT-23 | 72K/7002 | 3000 |

Absolute Maximum Ratings (Tc=25°Cunless otherwise noted)

| Symbol | Parameter | Limit | Unit | |
|---------|---|----------------------|------------|--------------|
| Vds | Drain-Source Voltage | | 60 | V |
| Vgs | Gate-Source Voltage | | ±20 | V |
| | | T _A =25℃ | 0.3 | |
| ID | Continuous Drain Current (T _J =150 $^{\circ}$ C) | T _A =100℃ | 0.19 | A |
| DM | Drain Current-Pulsed (Note 1) | | 0.8 | А |
| PD | Maximum Power Dissipation | 0.35 | W | |
| Tj,Tstg | Operating Junction and Storage Temperature Range | | -55 To 150 | °C |
| Reja | Thermal Resistance, Junction-to-Ambient (Note 2) | | 350 | °C /W |





N-Channel MOSFET



Electrical Characteristics (T_A=25[°]Cunless otherwise noted)

| Parameter | Symbol | Condition | Min | Тур | Мах | Unit |
|----------------------------------|-------------------|--|-----|------------|-------------|----------|
| Drain-Source Breakdown Voltage | BV _{DSS} | V _{GS} =0V I _D =250µA | 60 | 68 | - | V |
| Zero Gate Voltage Drain Current | ldss | V _{DS} =60V,V _{GS} =0V | - | - | 1 | μA |
| Gate-Body Leakage Current | lgss | V _{GS} =±10V,V _{DS} =0V V _{GS} =±20V,V _{DS} =0V | - | ±100 ±4 | ±500 ±10 | nA uA |
| Gate Threshold Voltage | VGS(th) | V _{DS} =V _{GS} ,I _D =250µA | 0.7 | 1.2 | 1.9 | V |
| | | V _{GS} =5V, I _D =0.1A | - | 1.3 | 3 | Ω |
| Drain-Source On-State Resistance | Rds(on) | V _{GS} =10V, I _D =0.1A | - | 1 | 2 | Ω |
| Forward Transconductance | gfs | V _{DS} =10V,I _D =0.2A | 0.1 | - | - | S |
| Input Capacitance | C _{lss} | | - | 21 | 50 | PF |
| Output Capacitance | Coss | V _{DS} =25V,V _{GS} =0V, F=1.0MHz | - | 11 | 25 | PF |
| Reverse Transfer Capacitance | Crss | F = 1.0101112 | - | 4.2 | 5 | PF |
| Turn-on Delay Time | td(on) | | - | 10 | - | nS |
| Turn-on Rise Time | tr | VDD=30V,ID=0.2A | - | 50 | - | nS |
| Turn-Off Delay Time | td(off) | V_{GS} =10V,R _{GEN} =10 Ω | - | 17 | - | nS |
| Turn-Off Fall Time | t _f | | - | 10 | - | nS |
| Total Gate Charge | Qg | V _{DS} =10V,I _D =0.3A, V _{GS} =4.5V | - | 1.7 | 3 | nC |
| Diode Forward Voltage (Note 3) | Vsd | V _{GS} =0V,I _S =0.2A | - | - | 1.2 | V |
| Diode Forward Current (Note 2) | Is | | - | - | 0.3 | Α |

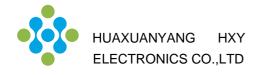
Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.

2. Surface Mounted on FR4 Board, $t \le 10$ sec.

3. Pulse Test: Pulse Width \leq 300µs, Duty Cycle \leq 2%.

4. Guaranteed by design, not subject to production



Typical Electrical And Thermal Characteristics

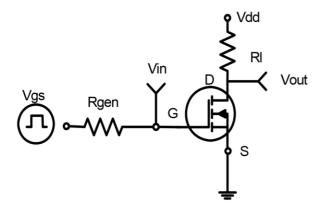


Figure 1:Switching Test Circuit

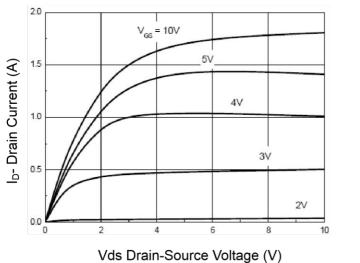
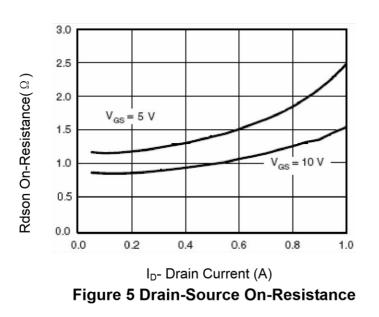


Figure 3 Output Characteristics



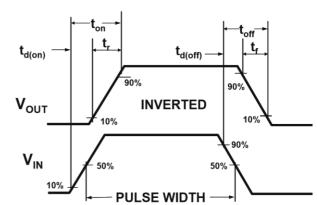


Figure 2:Switching Waveforms

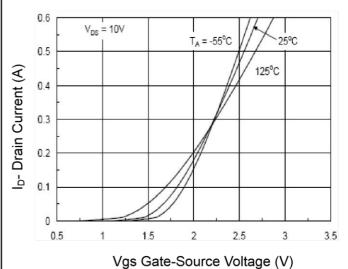
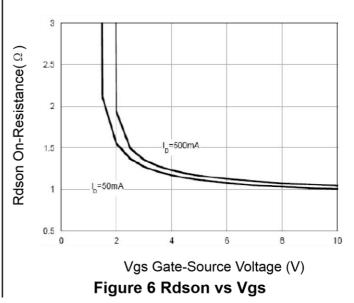
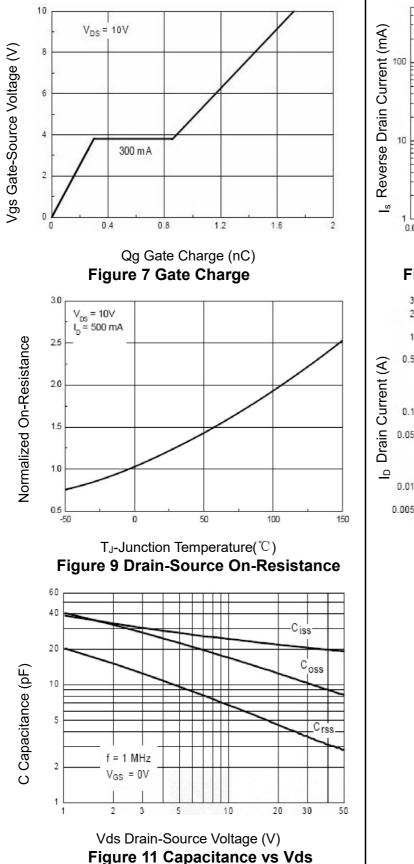
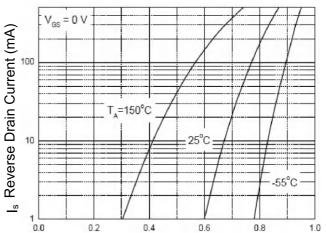


Figure 4 Transfer Characteristics

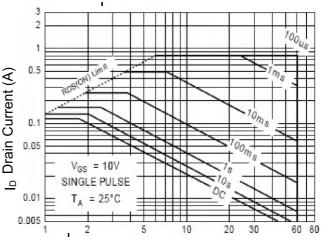




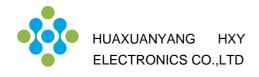




Vsd Source-Drain Voltage (V) Figure 8 Source-DrainDiode Forward



Vds Drain-Source Voltage (V) Figure 10 Safe Operation Area



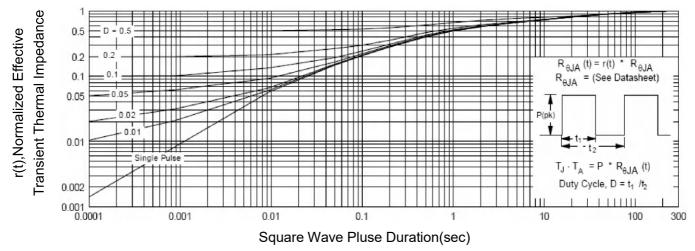
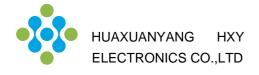
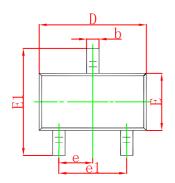
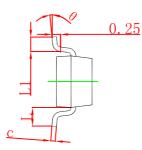


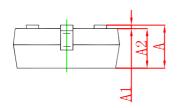
Figure 12 Normalized Maximum Transient Thermal Impedance



SOT-23 Package Outline Dimensions

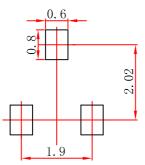






| Symbol | Dimensions In Millimeters | | Dimensions In Inches | | |
|--------|---------------------------|-------|----------------------|-------|--|
| | Min | Max | Min | Max | |
| Α | 0.900 | 1.150 | 0.035 | 0.045 | |
| A1 | 0.000 | 0.100 | 0.000 | 0.004 | |
| A2 | 0.900 | 1.050 | 0.035 | 0.041 | |
| b | 0.300 | 0.500 | 0.012 | 0.020 | |
| С | 0.080 | 0.150 | 0.003 | 0.006 | |
| D | 2.800 | 3.000 | 0.110 | 0.118 | |
| Е | 1.200 | 1.400 | 0.047 | 0.055 | |
| E1 | 2.250 | 2.550 | 0.089 | 0.100 | |
| е | 0.950 |) TYP | 0.037 TYP | | |
| e1 | 1.800 | 2.000 | 0.071 | 0.079 | |
| L | 0.550 REF | | 0.022 REF | | |
| L1 | 0.300 | 0.500 | 0.012 | 0.020 | |
| θ | 0° | 8° | 0° | 8° | |

SOT-23 Suggested Pad Layout



Note: 1.Controlling dimension:in millimeters.

2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.



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